

1/13

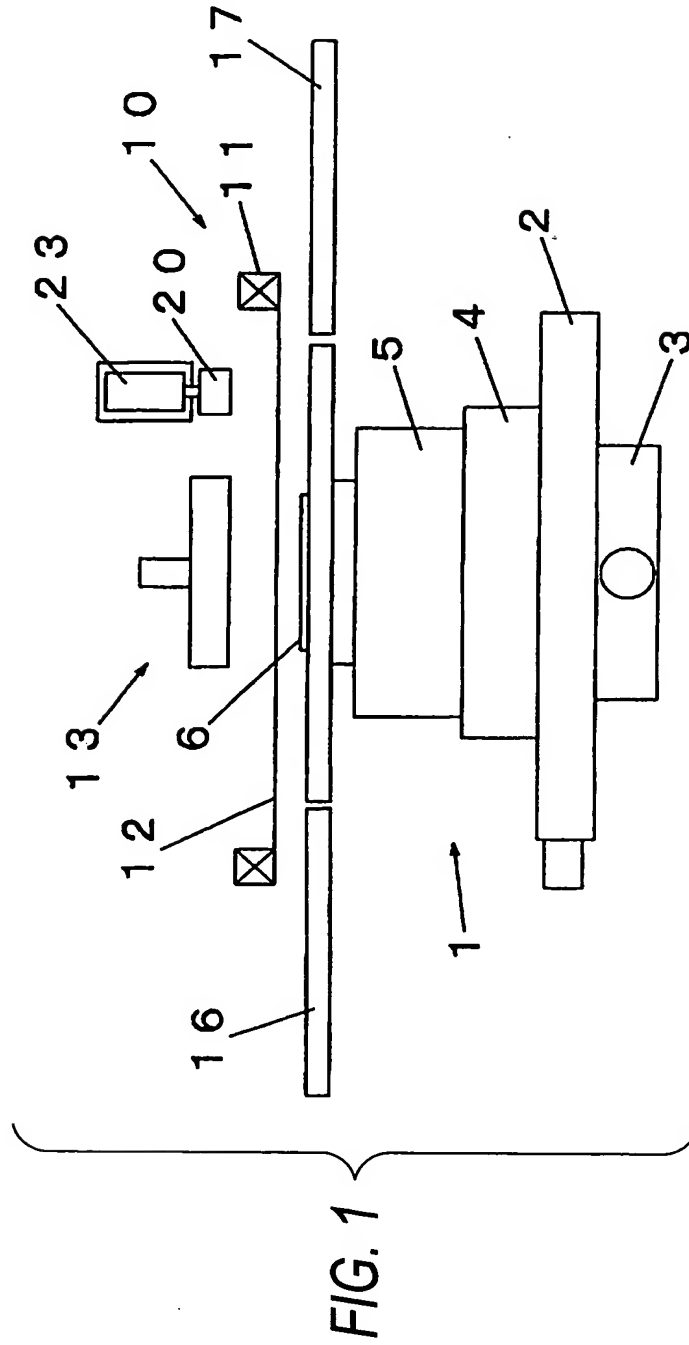




FIG. 2

FIG. 3

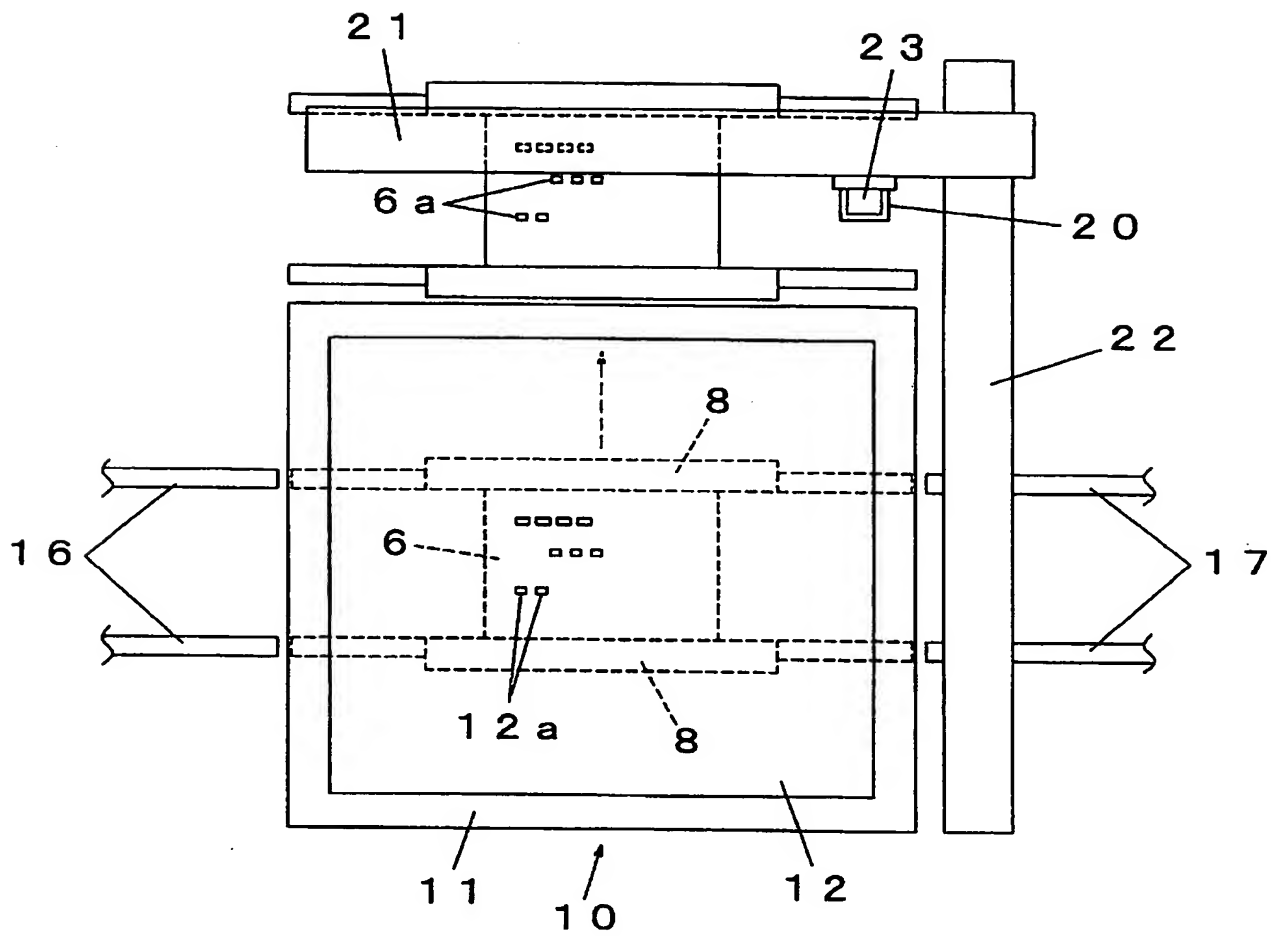


FIG. 4

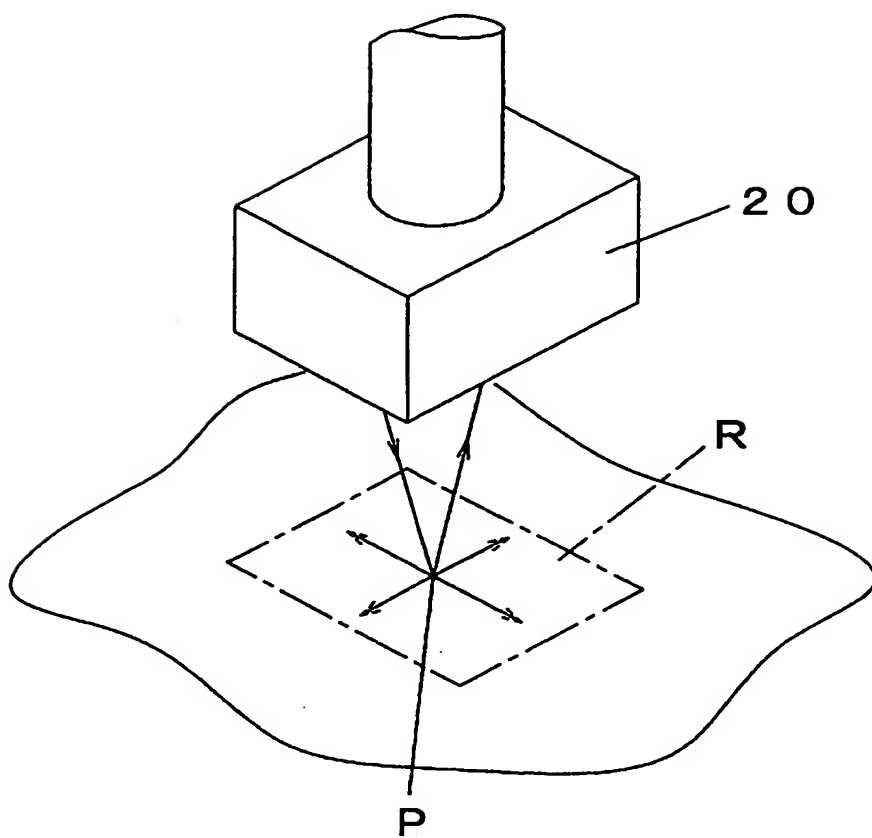


FIG. 5

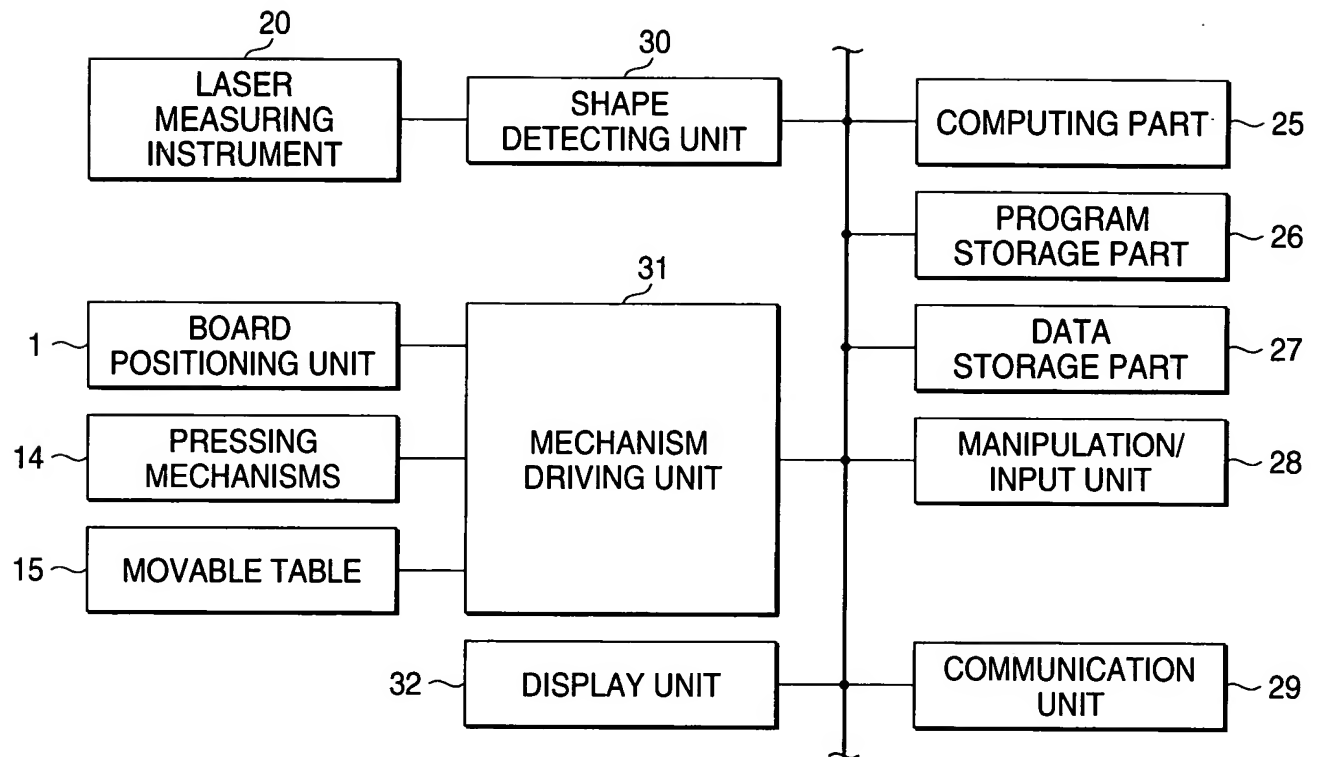


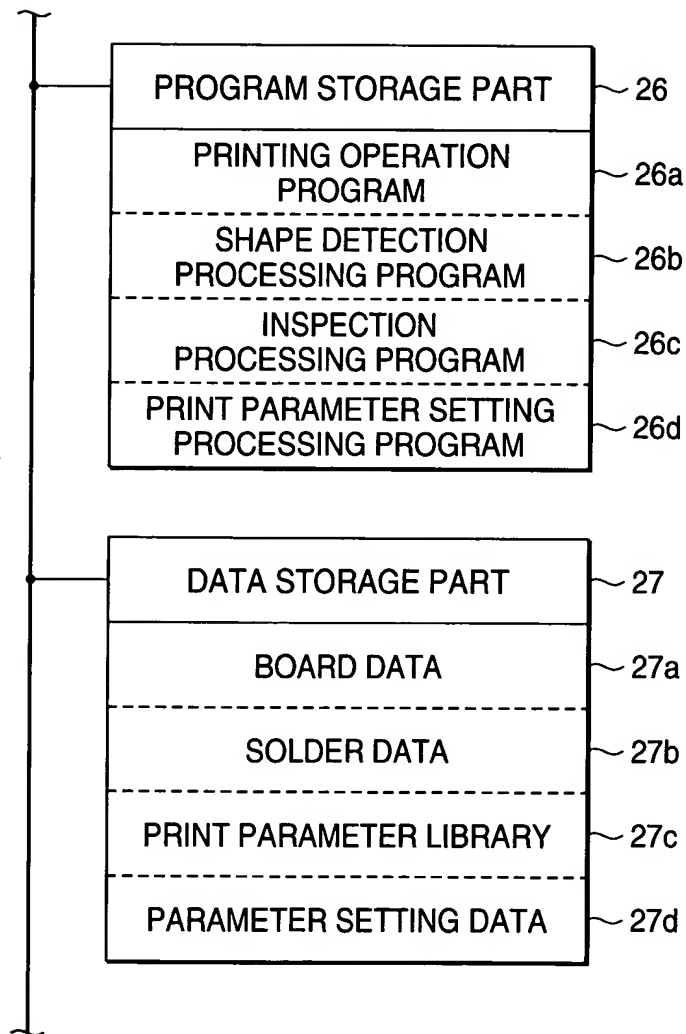
FIG. 6

FIG. 7

| PATTERN NAME | A | B | C | |
|-------------------------|----|----|-----|--|
| PARAMETER \ SOLDER TYPE | S1 | S2 | S3 | |
| SQUEEGEE MOVEMENT SPEED | V1 | V2 | V3 | |
| PRINTING PRESSURE | P1 | P2 | P3 | |
| PLATE RELEASE PATTERN | I | II | III | |
| PLATE RELEASE SPEED | v1 | v2 | v3 | |
| | | | | |

FIG. 8

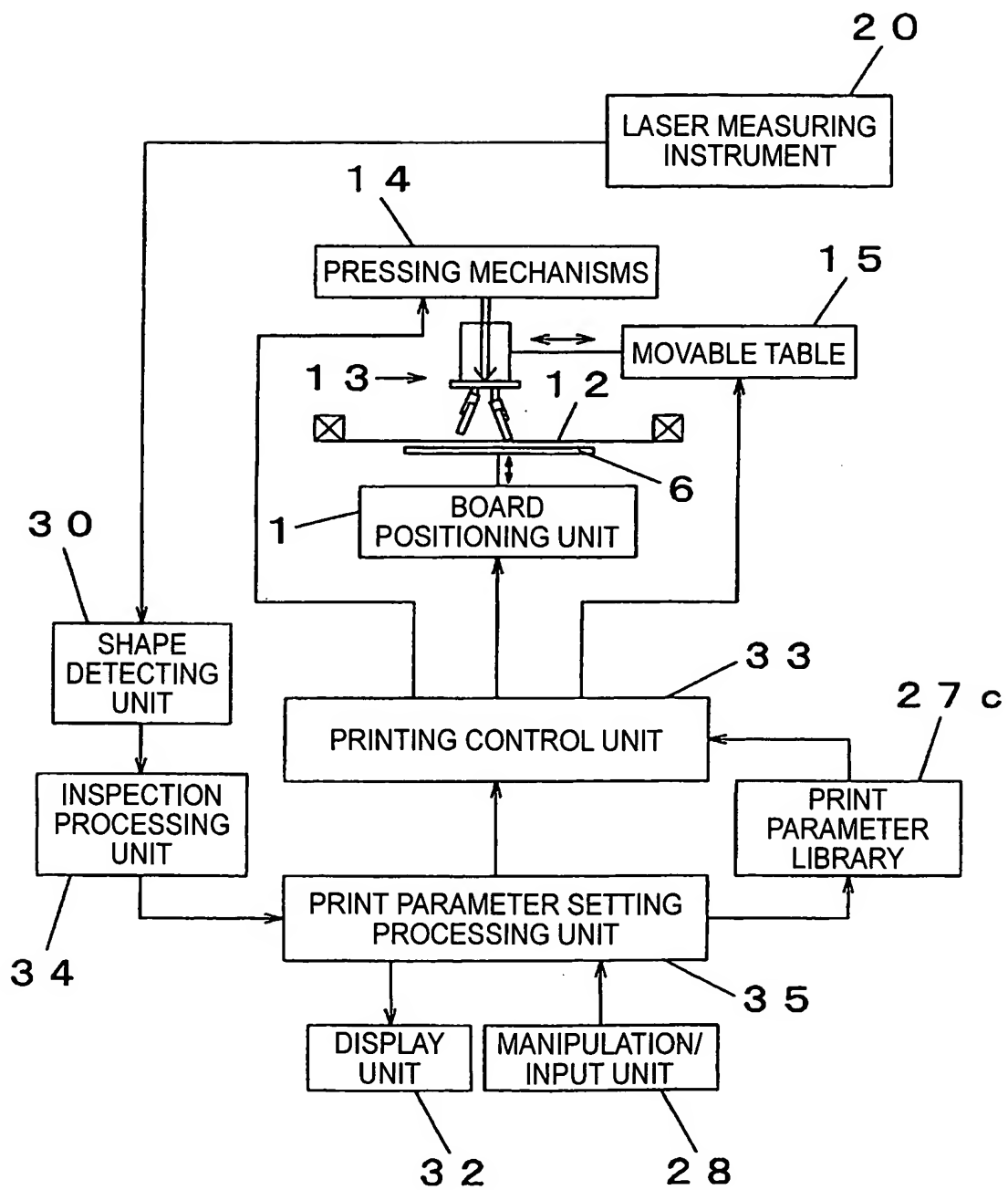


FIG. 9

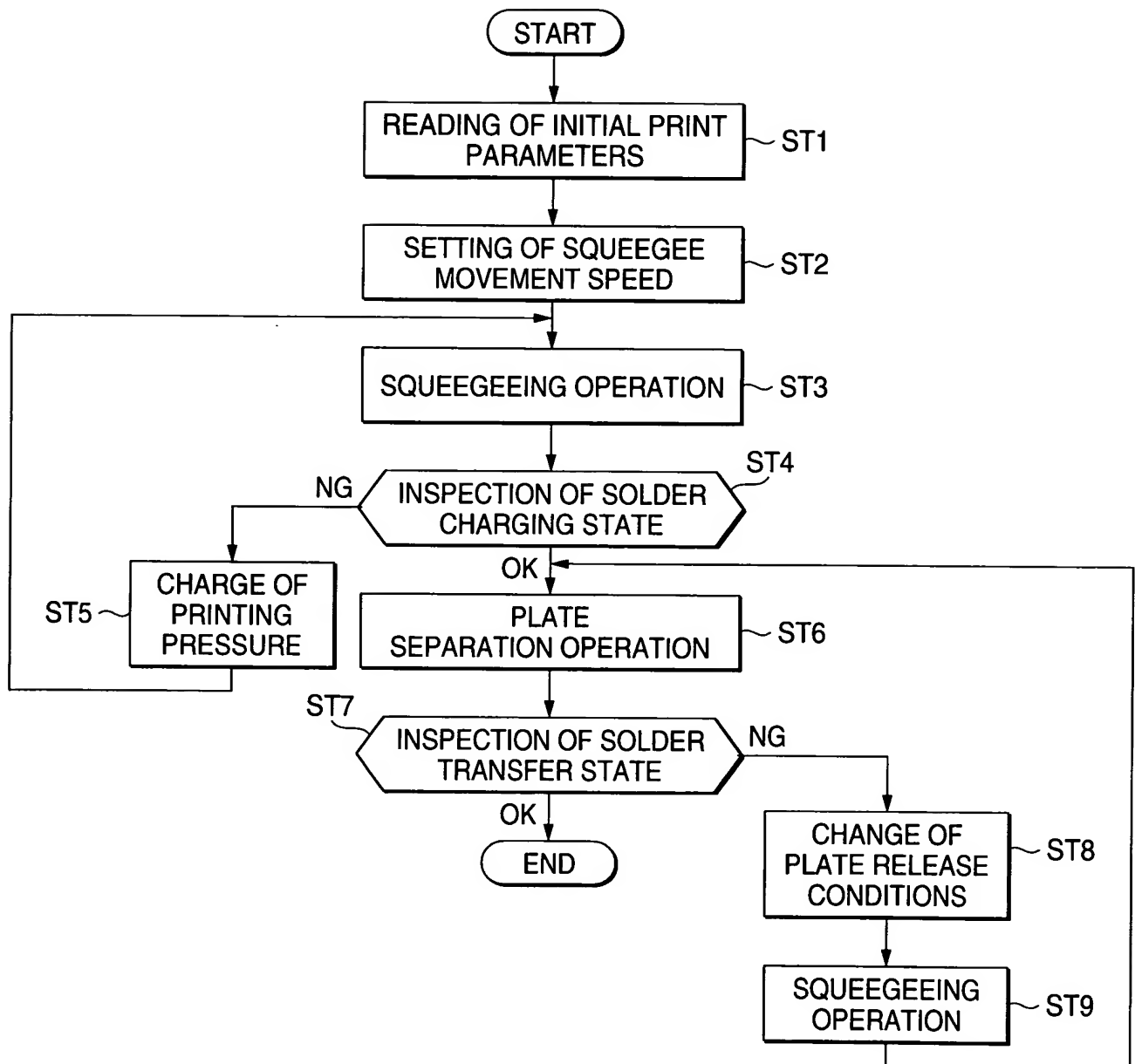


FIG. 10 (a)

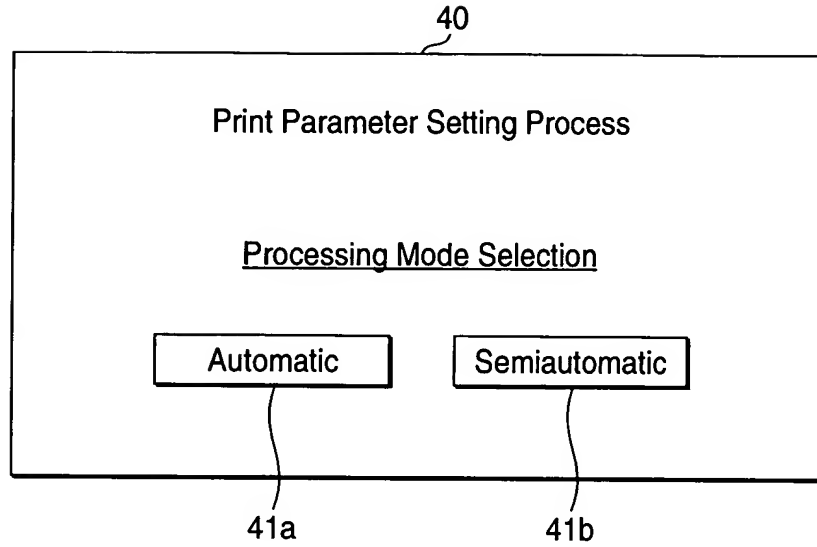


FIG. 10 (b)

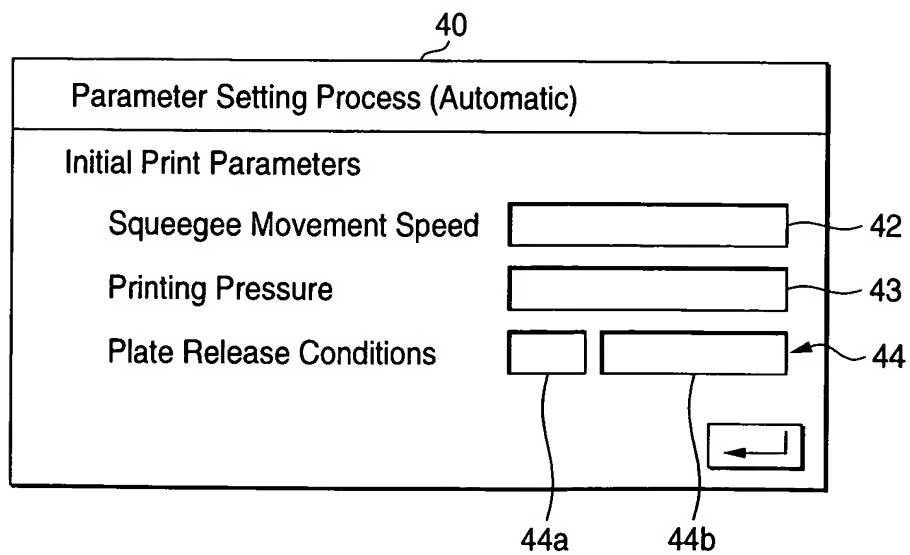


FIG. 11 (a)

40

Parameter Setting Process (Automatic)

Parameter Confirmation

Squeegee Movement Speed

42

Printing Pressure

43

Plate Release Conditions

44

OK

45a

Re-Setting

45b

FIG. 11 (b)

40

Parameter Setting Process (Automatic)

Parameter Name

46

Solder Type

47

Registration

48

FIG. 12

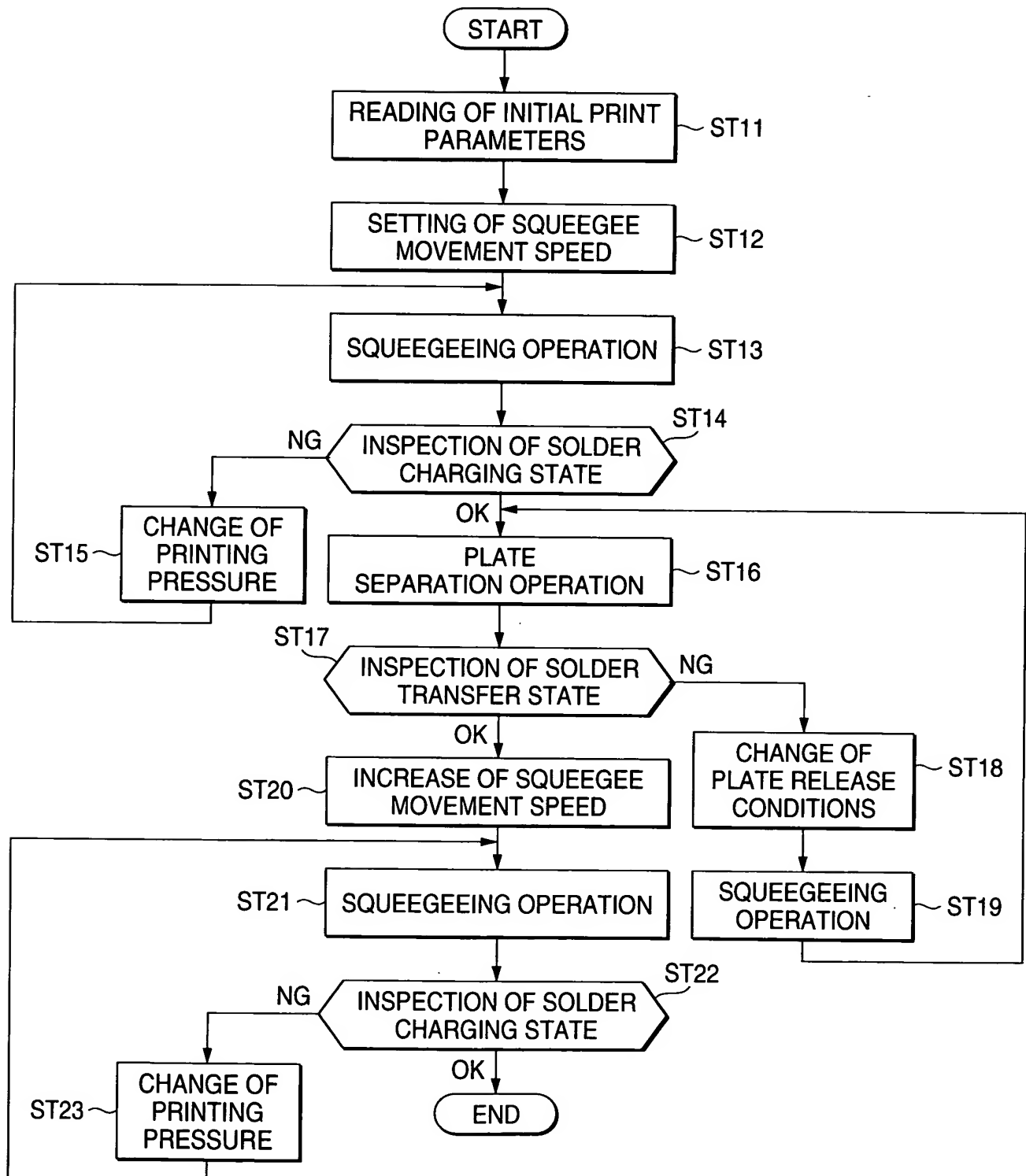


FIG. 13 (a)

40

Parameter Setting Process (Semiautomatic)

Step 1

Squeegee Movement Speed 49

FIG. 13 (b)

40

Parameter Setting Process (Semiautomatic)

Squeegee Movement Speed 50

Step 2

Printing Pressure 51

FIG. 13 (c)

40

Parameter Setting Process (Semiautomatic)

Squeegee Movement Speed 50

Printing Pressure 52

Step 3

Plate Release Conditions 53a 53b 53